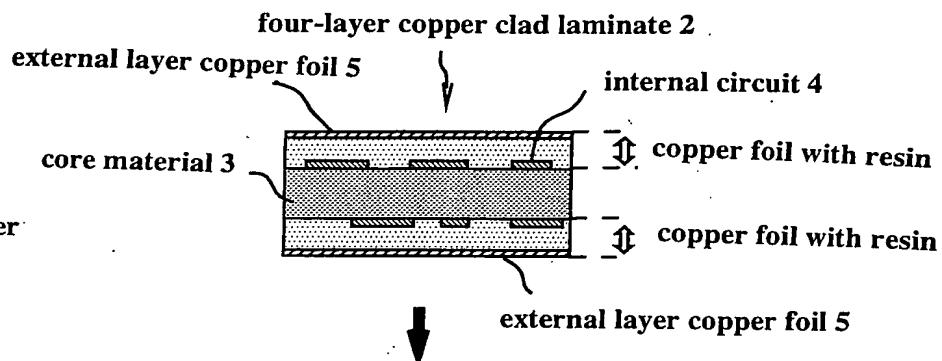


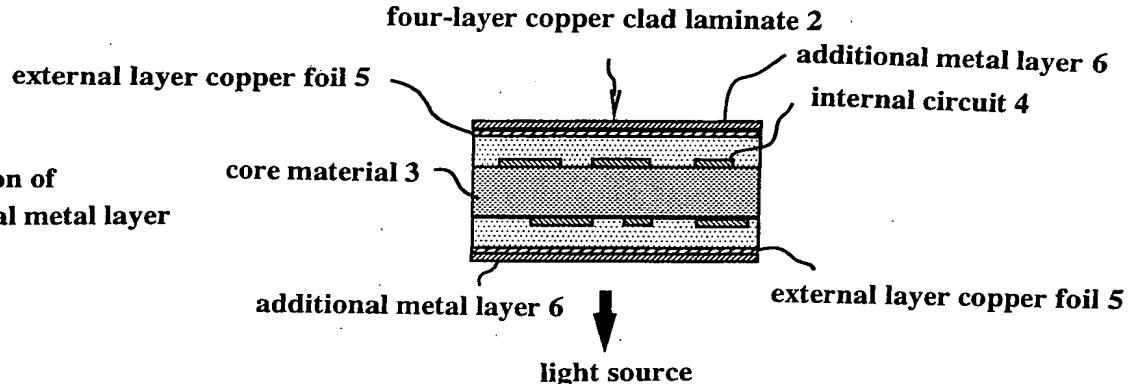
FIG. 1



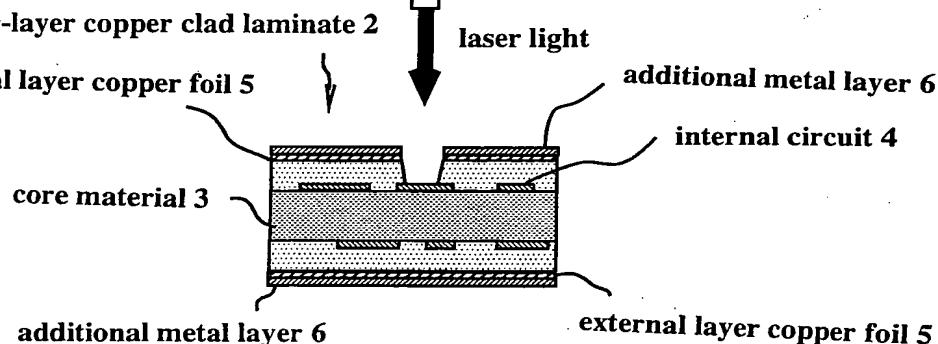
(a) Manufacture of four-layer copper clad laminate



(b) Formation of additional metal layer



(c) Hole-drilling by laser



(d) Peeling-off of an additional metal layer

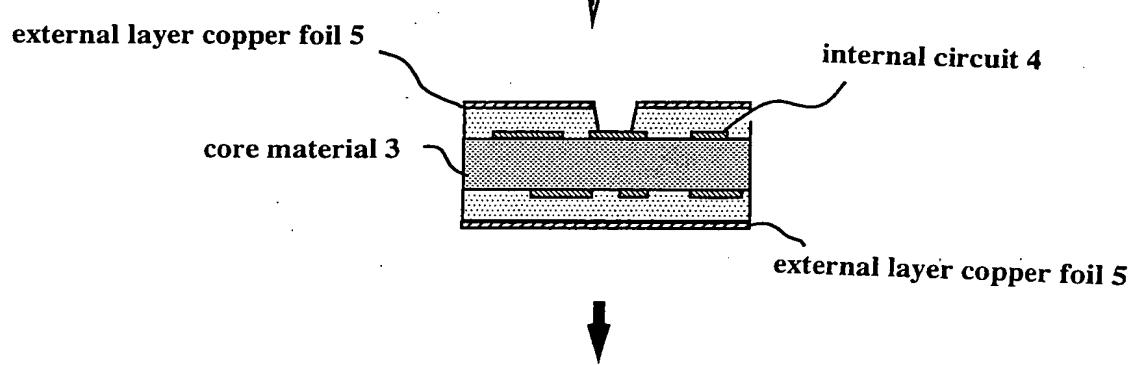


FIG. 2

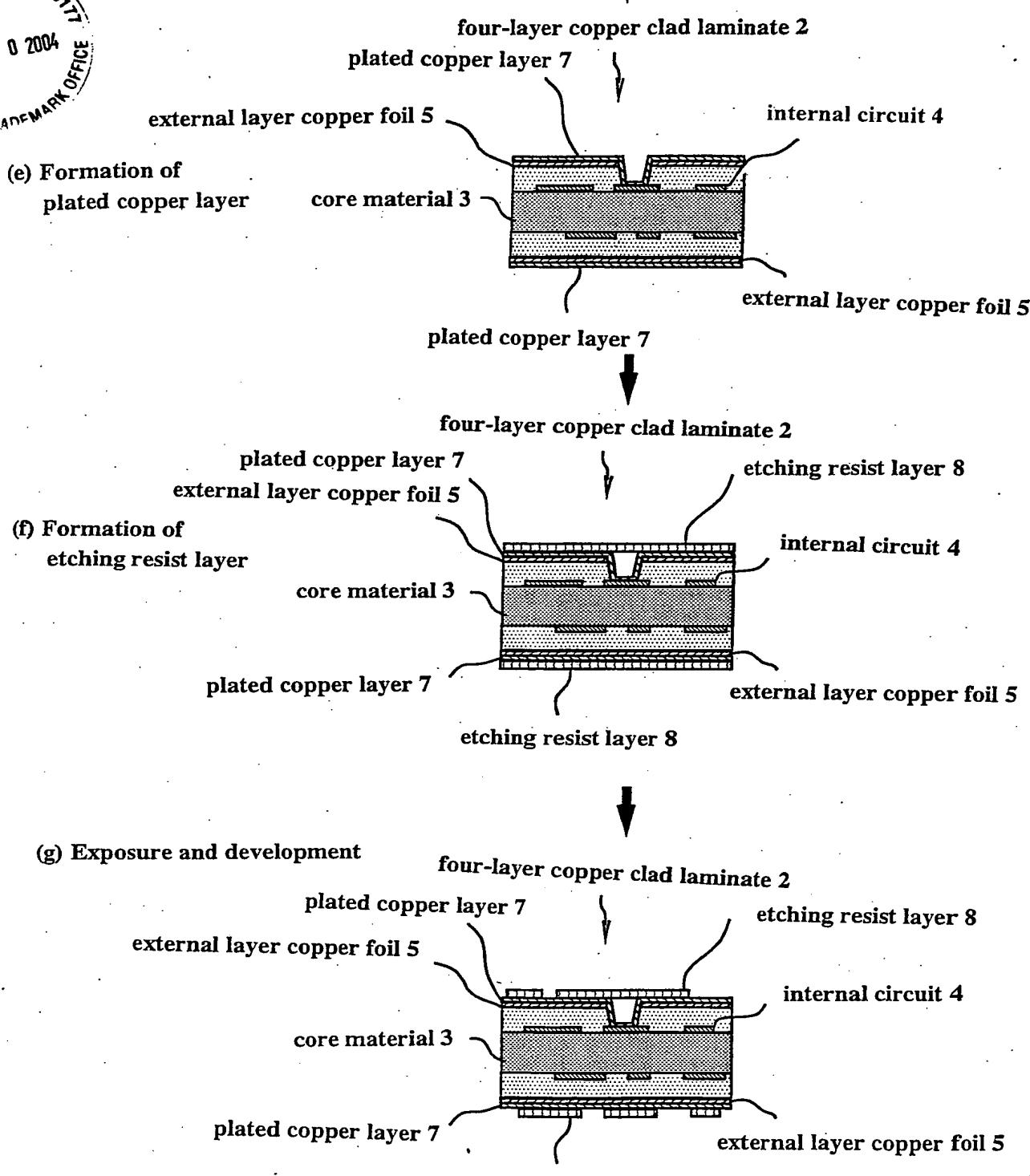
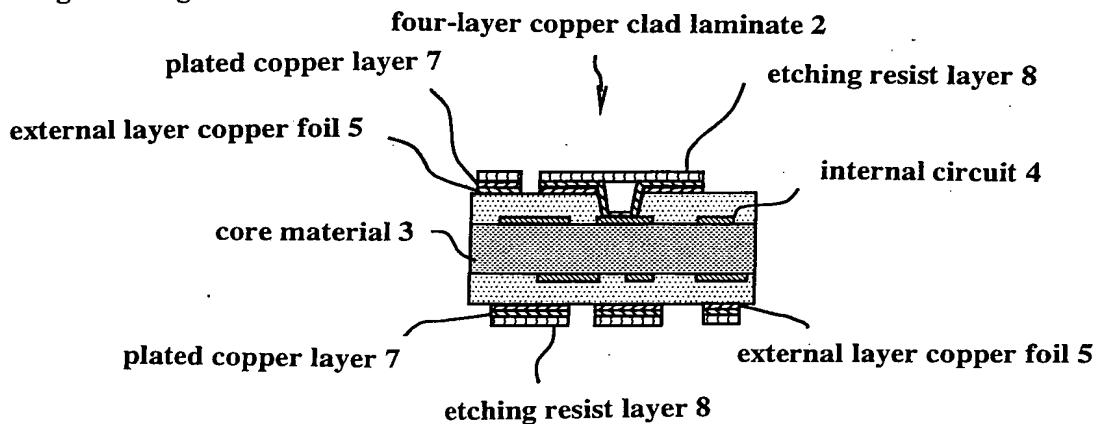


FIG. 3



(h) Formation of a circuit through etching



(i) Peeling-off of etching resist layer

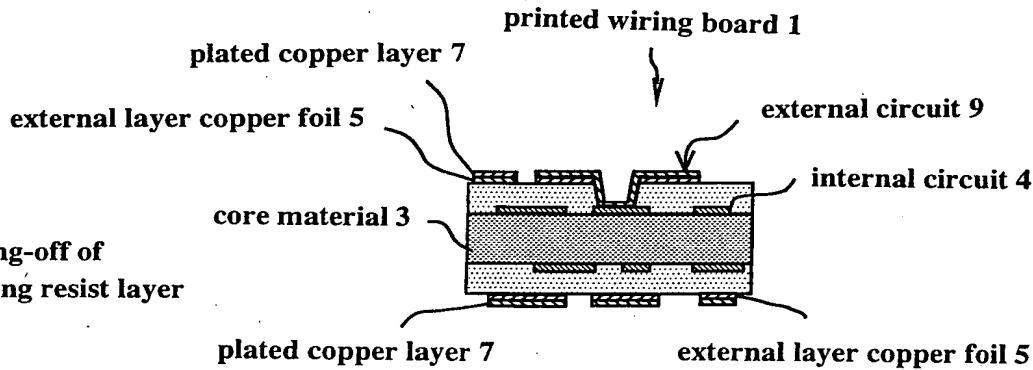
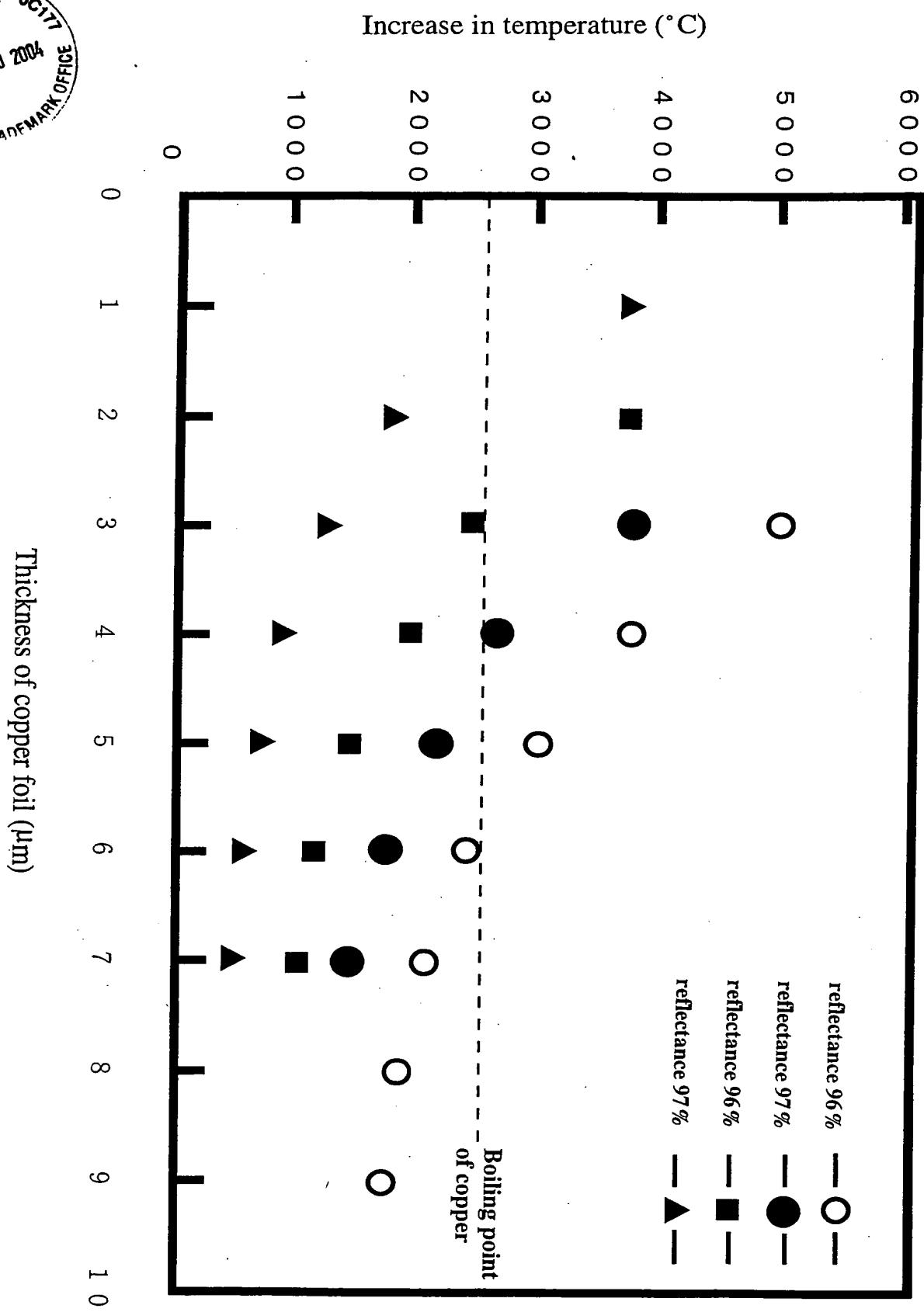


FIG. 4



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FIG. 5

Thickness of an additional metal layer / μm

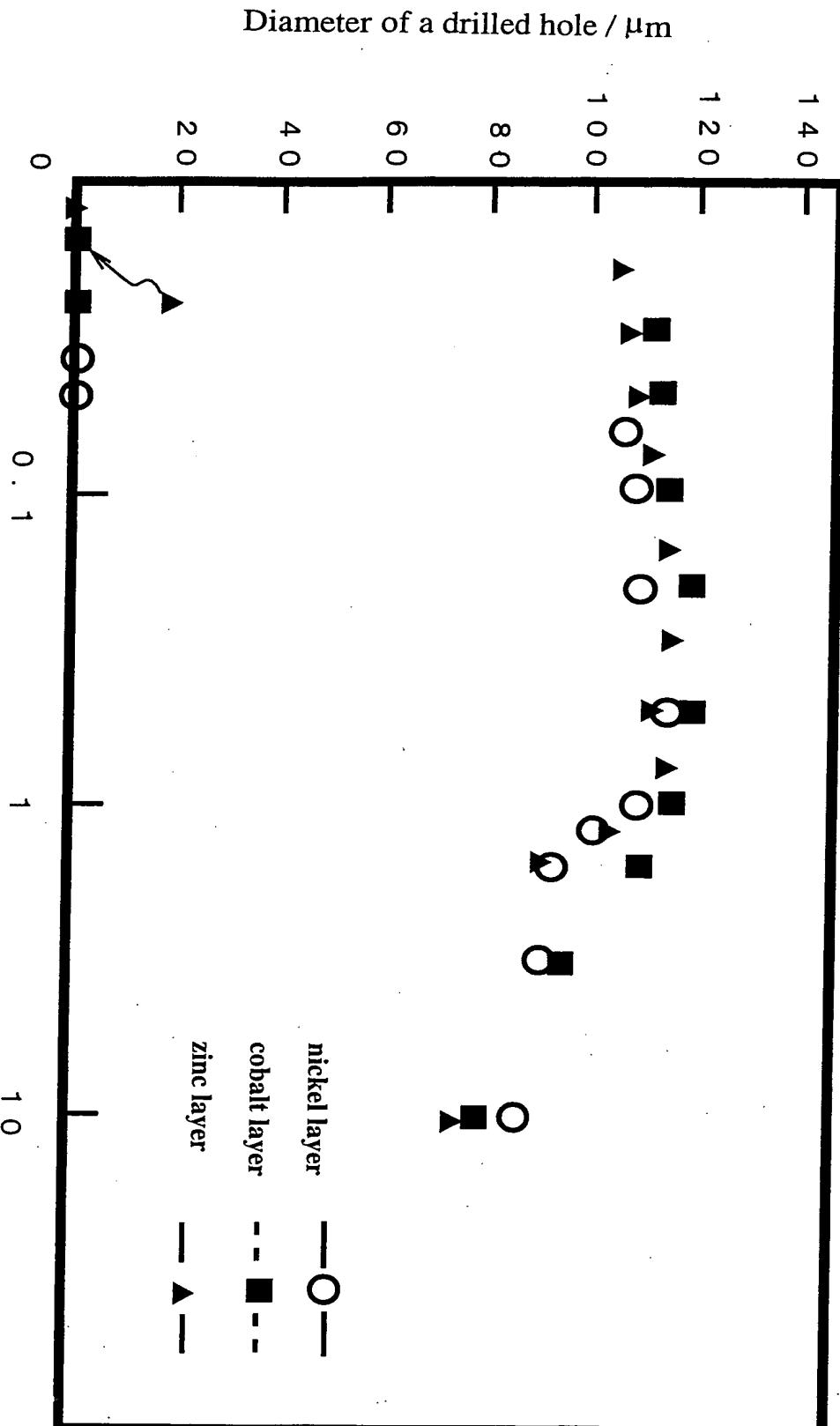
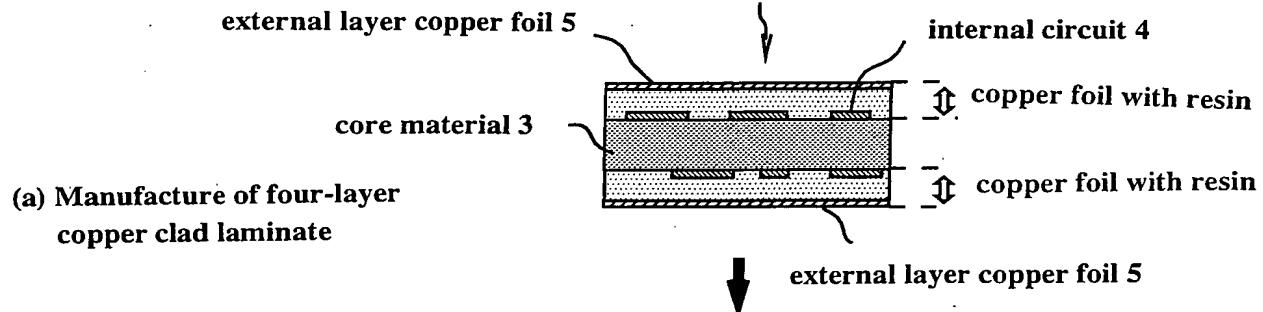


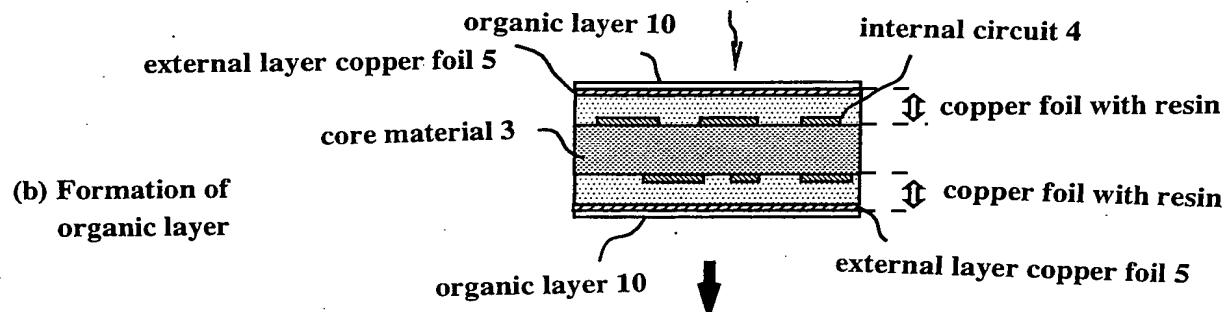
FIG. 6

four-layer copper clad laminate 2



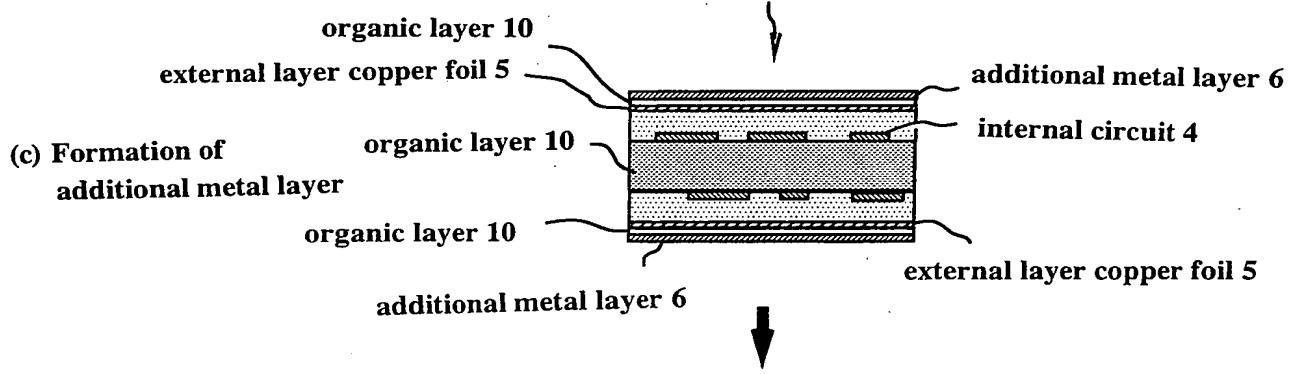
(a) Manufacture of four-layer copper clad laminate

four-layer copper clad laminate 2



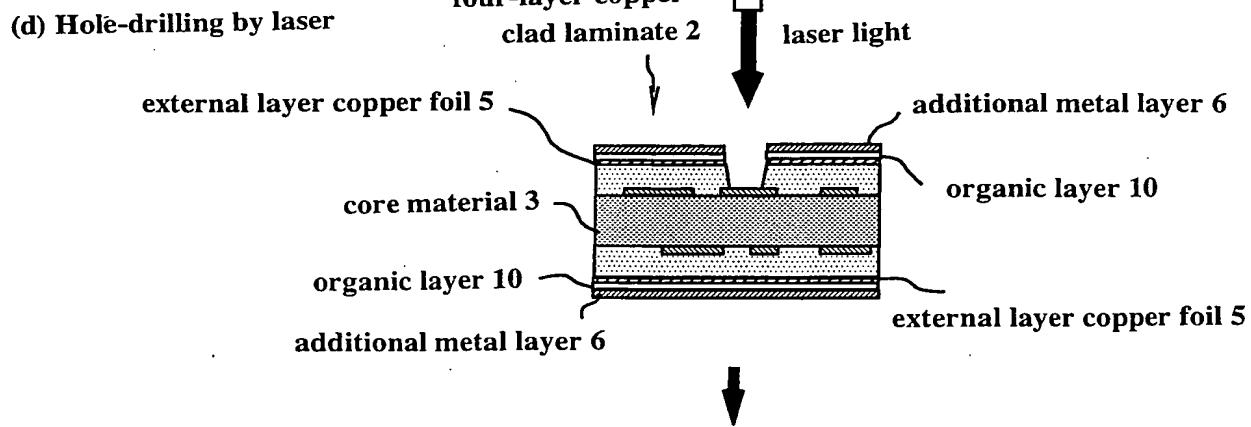
(b) Formation of organic layer

four-layer copper clad laminate 2



(c) Formation of additional metal layer

four-layer copper clad laminate 2

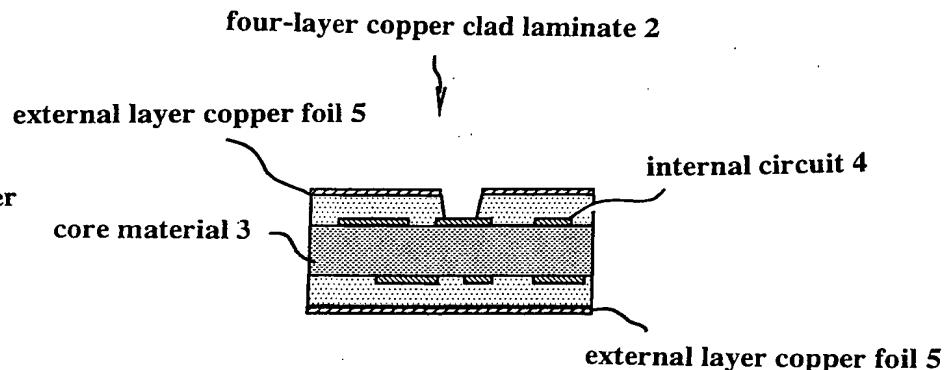


(d) Hole-drilling by laser

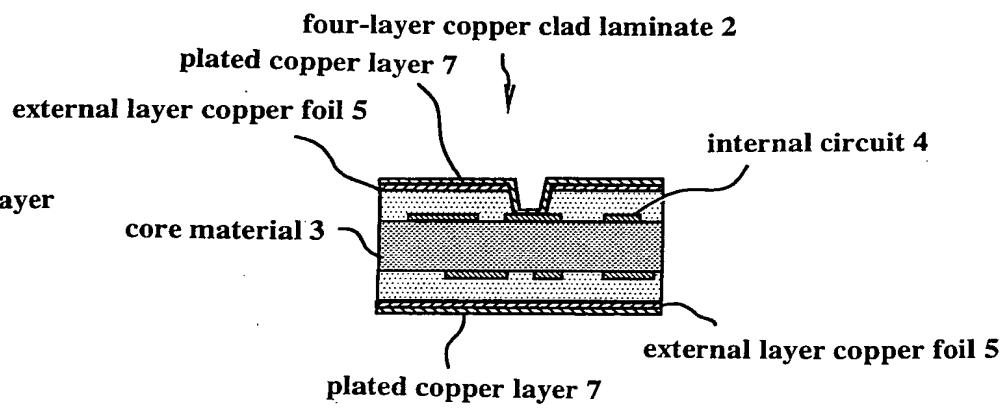
FIG. 7



(e) Peeling-off of
additional metal layer
and organic layer



(f) Formation of
plated copper layer



(g) Formation of
etching resist layer

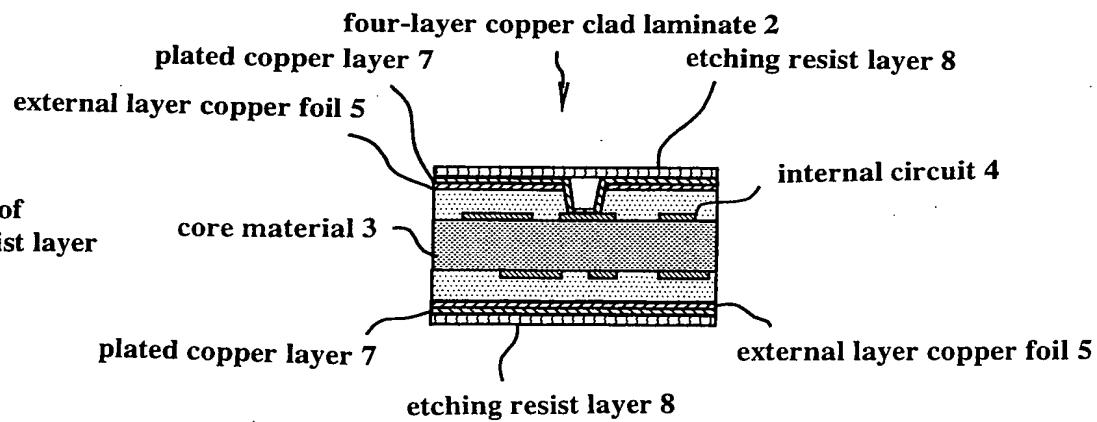
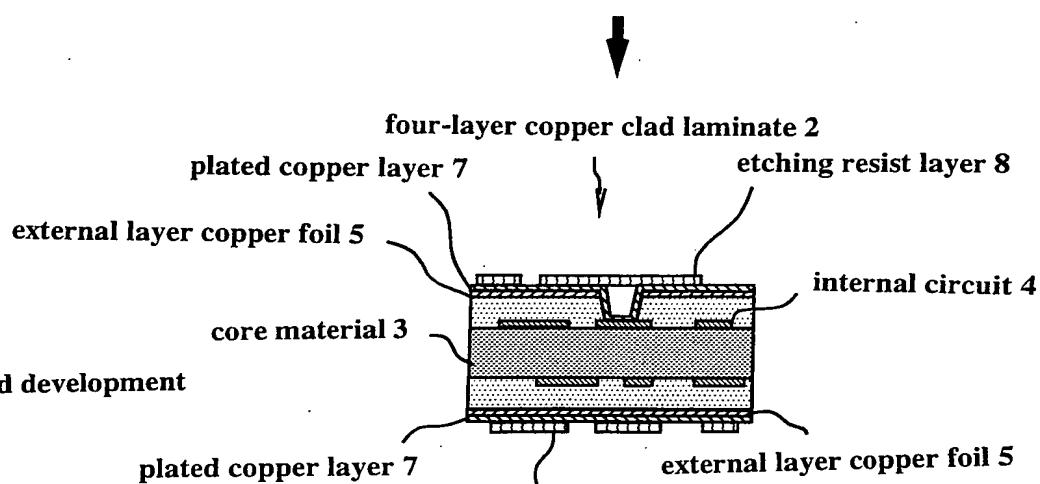


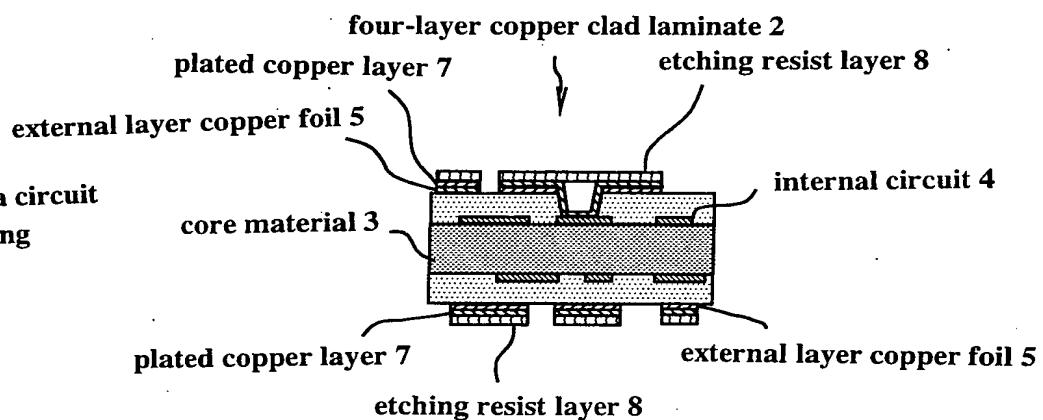
FIG. 8



(h) Exposure and development



(i) Formation of a circuit through etching



(j) Peeling-off of etching resist layer

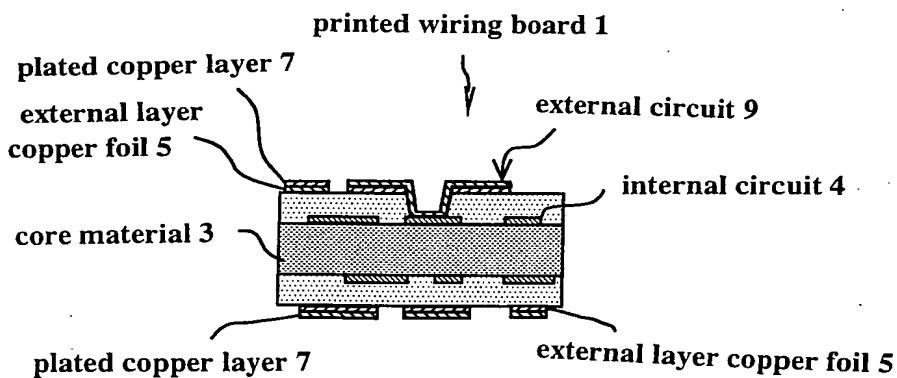


FIG. 9

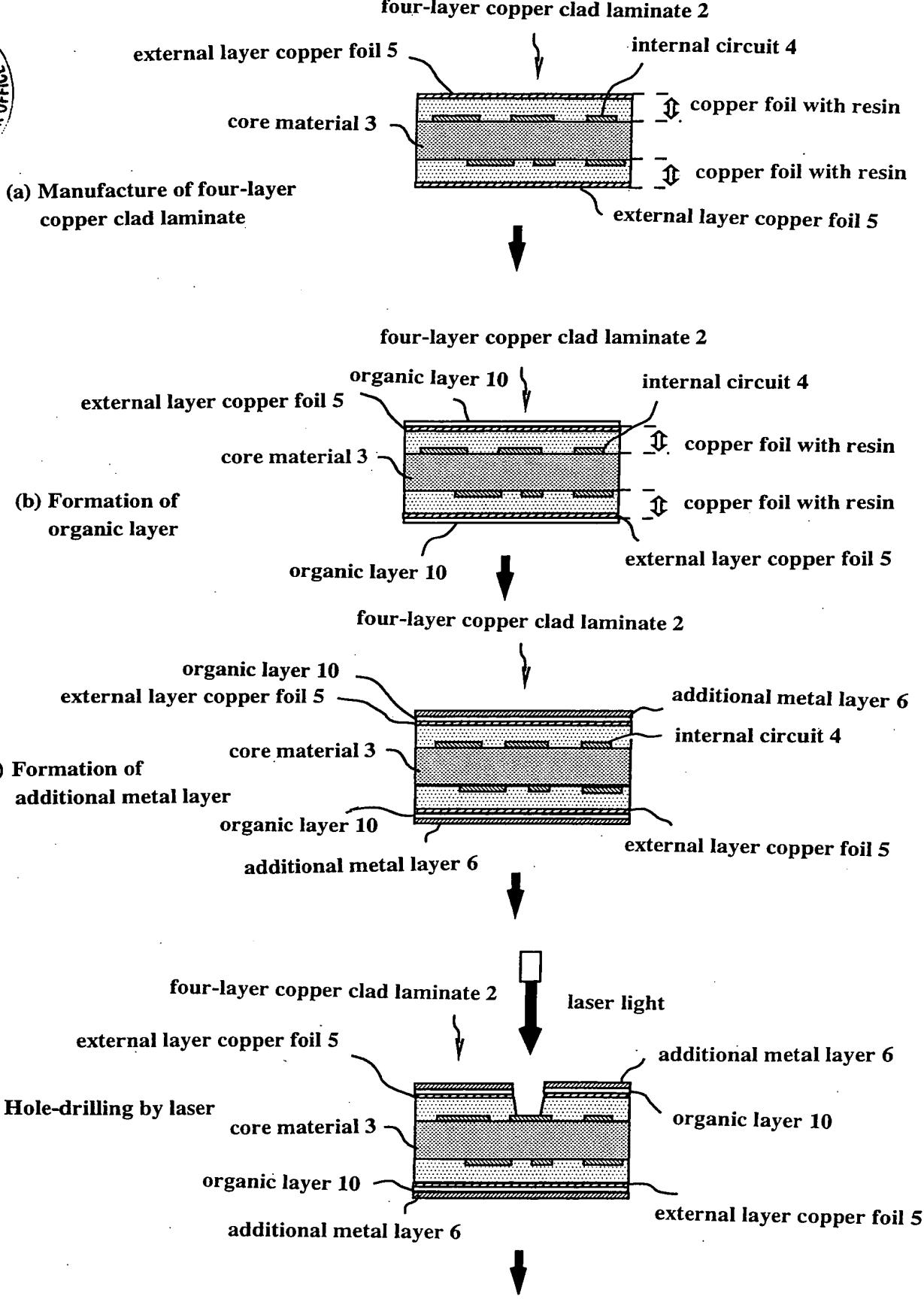
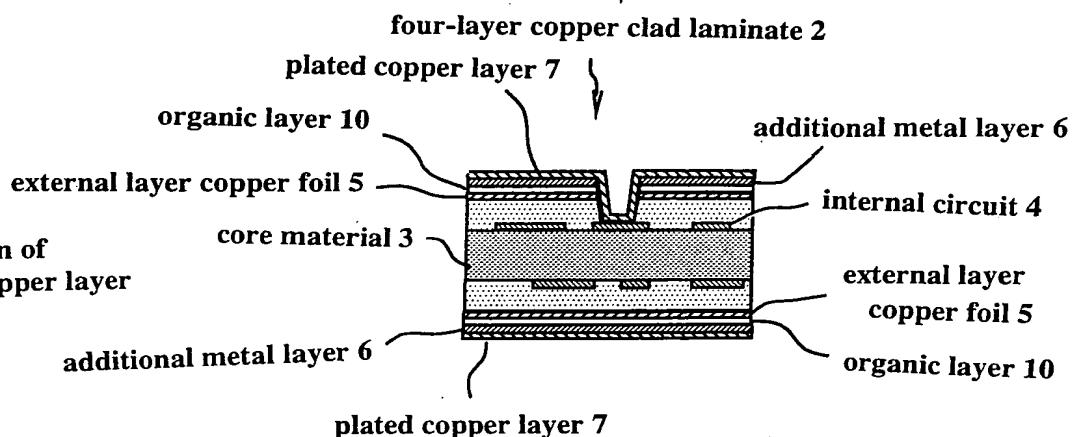


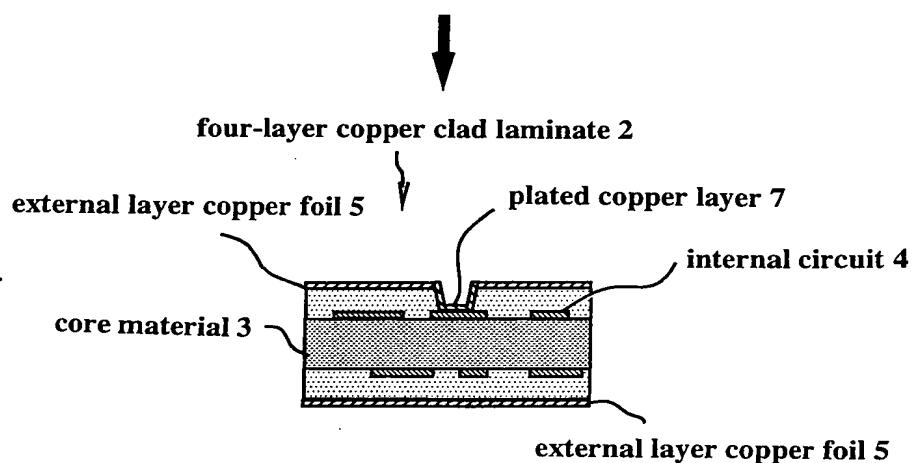
FIG. 10



(e) Formation of plated copper layer



(f) Peeling-off of additional metal layer and organic layer



(g) Formation of etching resist layer

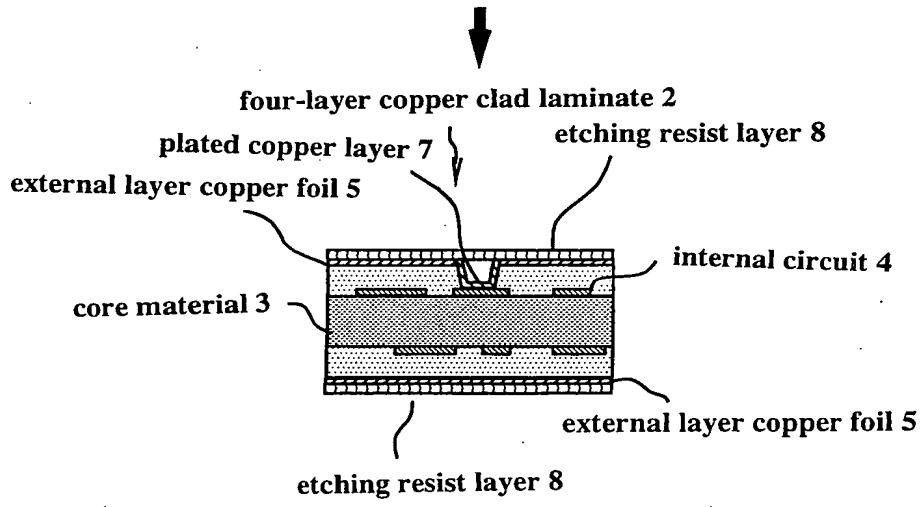


FIG. 11

